

Development and characterization of the latest X-ray SOI pixel sensor for a future astronomical mission

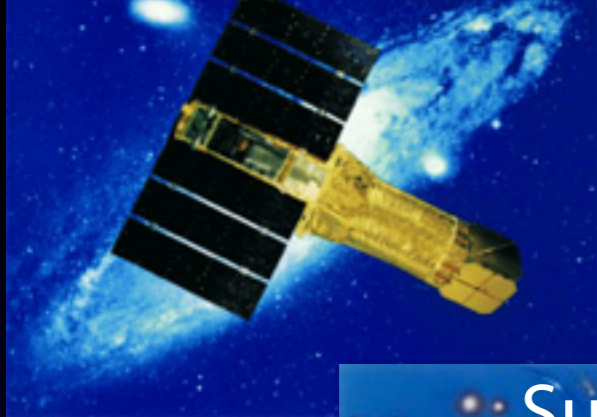
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Miyoshi, R. Ichimiya, T. Imamura, T. Ohmoto, A. Iwata
on behalf of the Japan SOI group

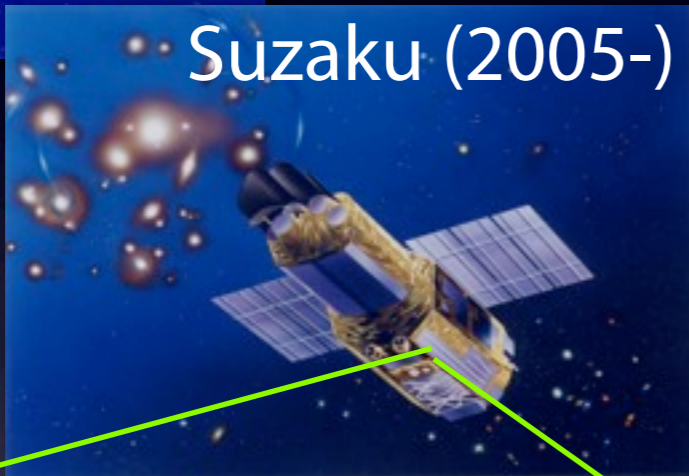


- ▶ Detectors for X-ray astronomy
- ▶ Our concept for the new detector
- ▶ Characterization of the latest device, "XRPIX2"

ASCA (1993-2000)



Suzaku (2005-)

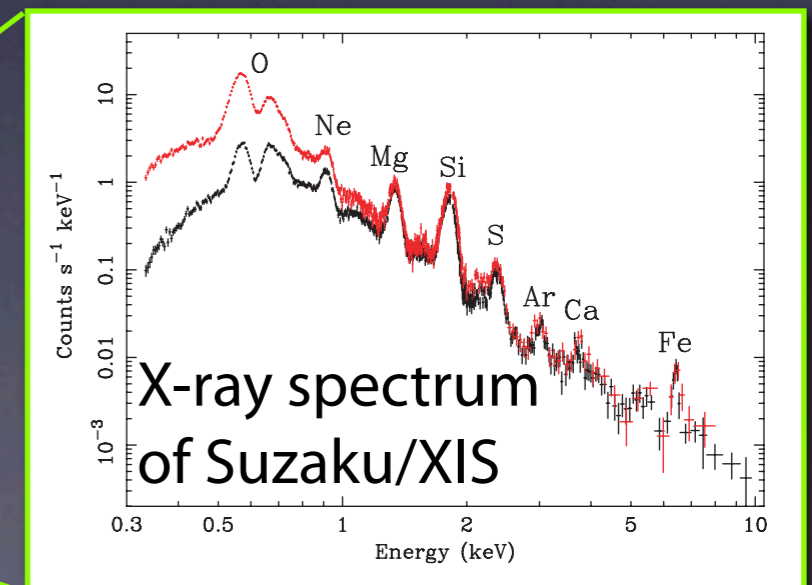
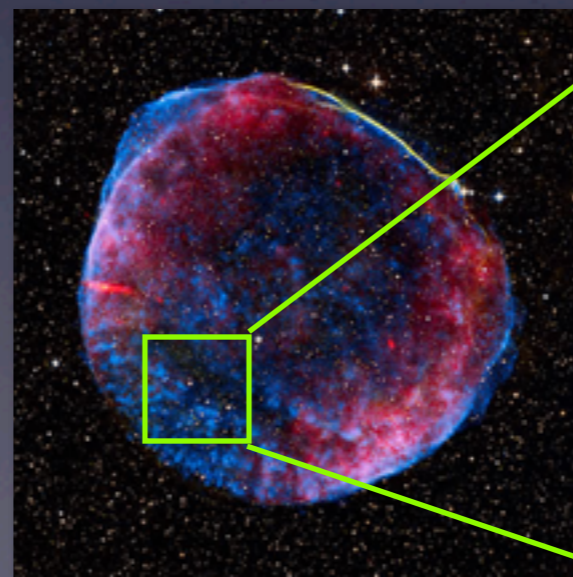
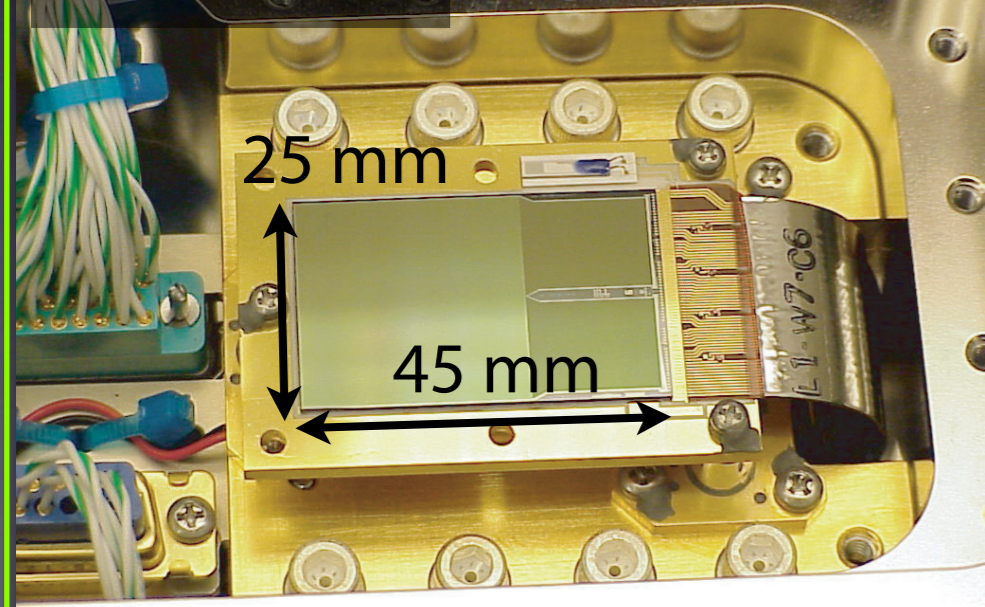


Detectors for X-ray astronomy are launched by satellites.

Since the ASCA satellite launched in 1993, CCDs are widely used for X-ray astronomy.

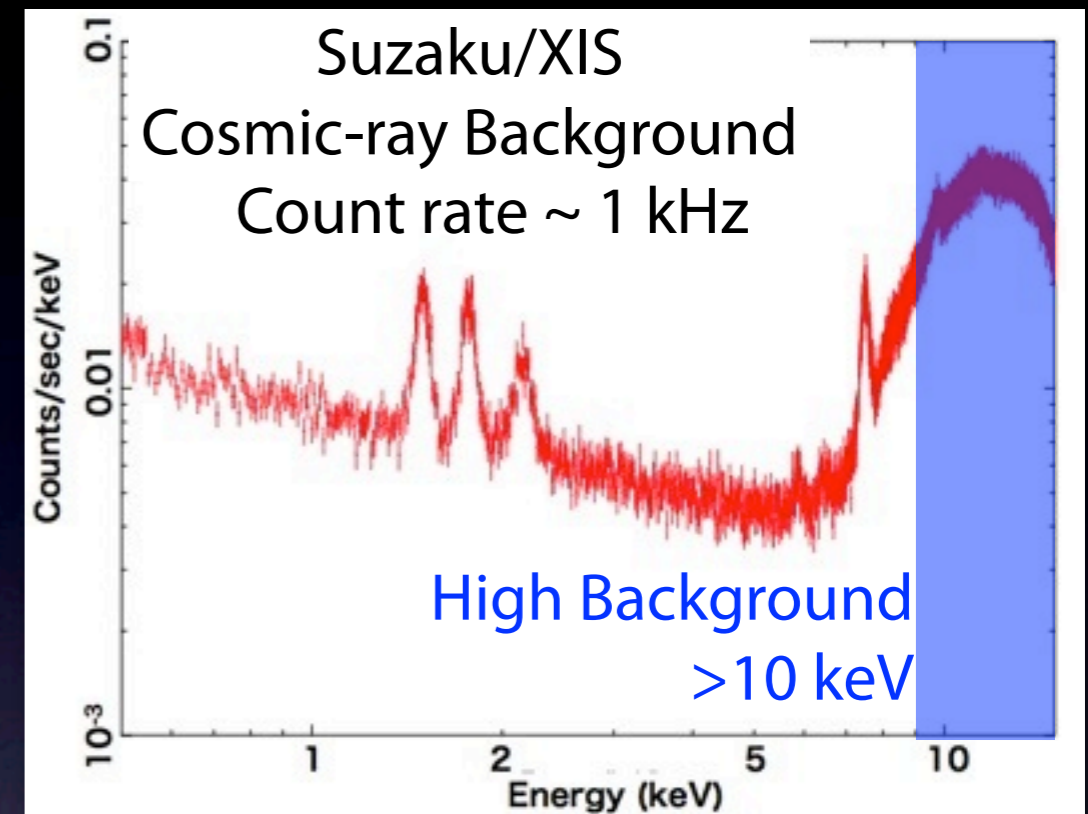
- ▶ Fine pixel pitch ($\sim 20 \mu\text{m}$)
- ▶ Fano limited energy resolution ($\sim 130 \text{ eV}$)
- ▶ High sensitivity for low energy X-ray (0.5 - 10 keV)

Suzaku/XIS



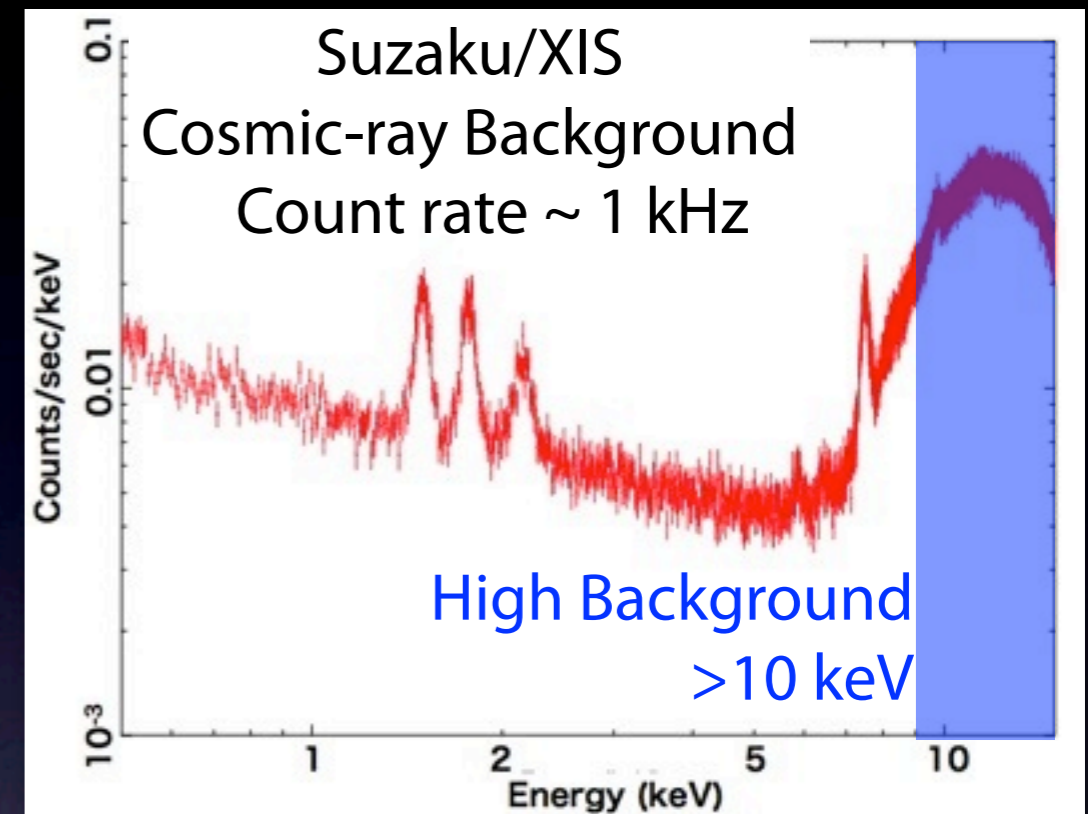
Problems of CCDs

- ▶ Charge transfer causes...
 - Low timing resolution (a few sec)
 - Charge loss due to lattice defects
 - > Radiation tolerance is low
- ▶ High background above 10 keV
 - > restricts hard X-ray observation

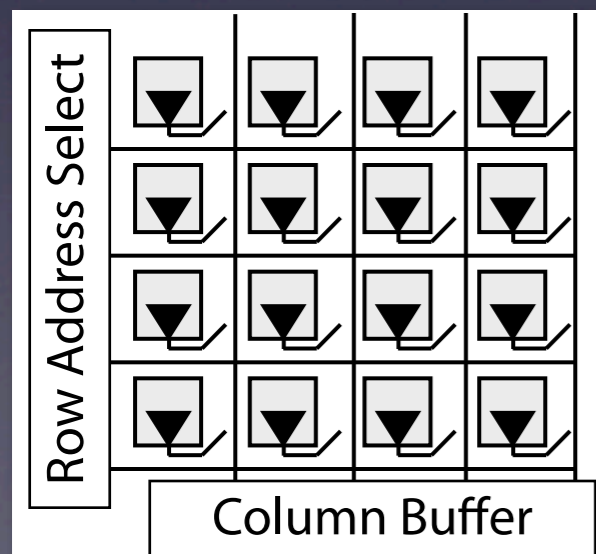


Problems of CCDs

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“Active Pixel Sensor” is being developed in various institutes



- ▶ Convert signal charge to voltage within a pixel
 - > Flexible readout pattern and faster timing resolution
 - > High tolerance to radiation damage
- ▶ Built-in integrated circuit

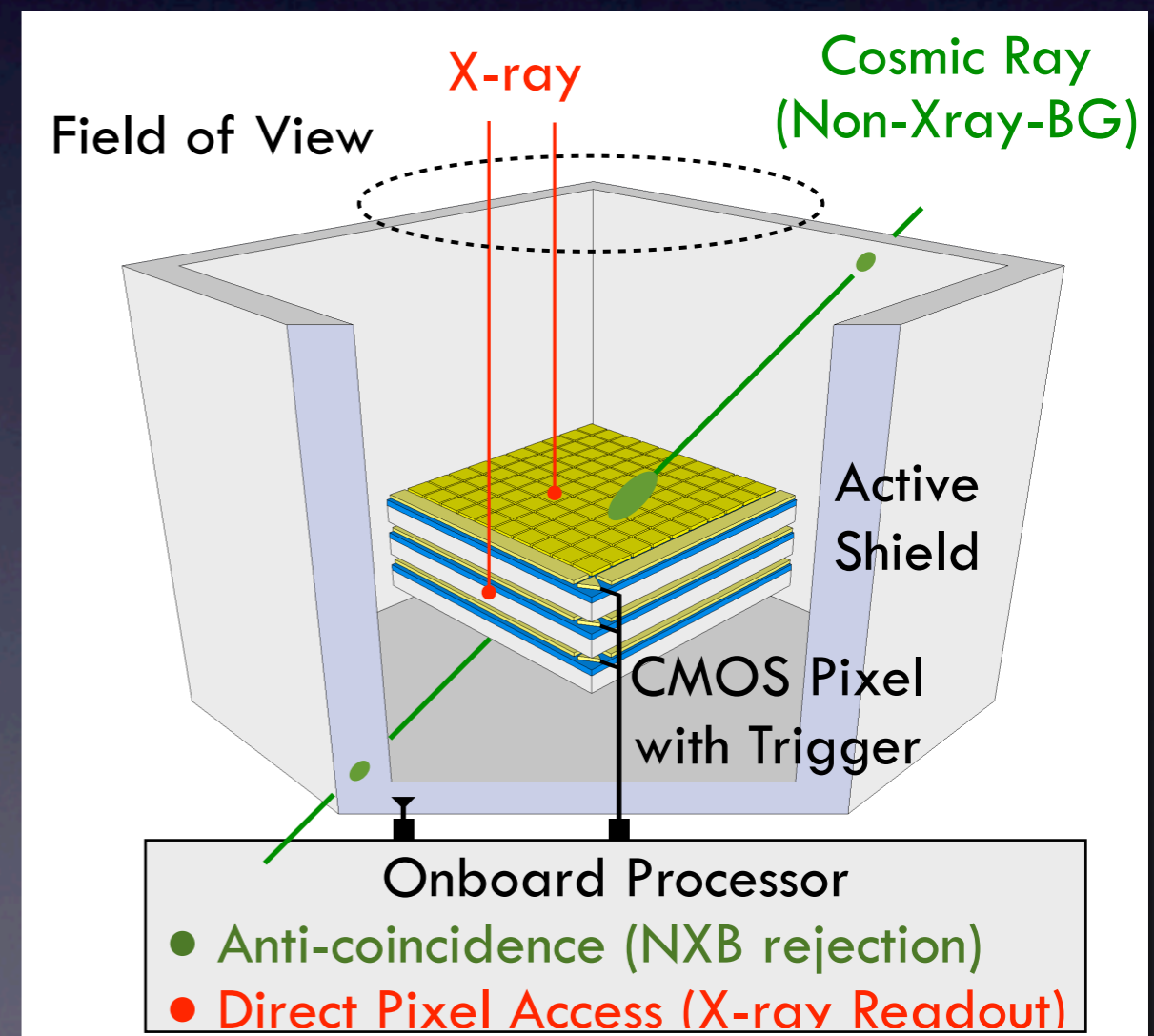
Our Concept = Intra-pixel trigger system

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	pixel pitch	Energy Resolution	Radiation Tolerance	Timing Resolution	Bandpass
CCD	<30 μm	Fano limited	Poor	~ 1 sec	0.5-10 keV
other APS	30-100 μm	Fano limited	Good	~ 1 msec	0.5-10 keV
our APS	<60 μm	Fano limited	Good	<1 μs	0.5-40 keV

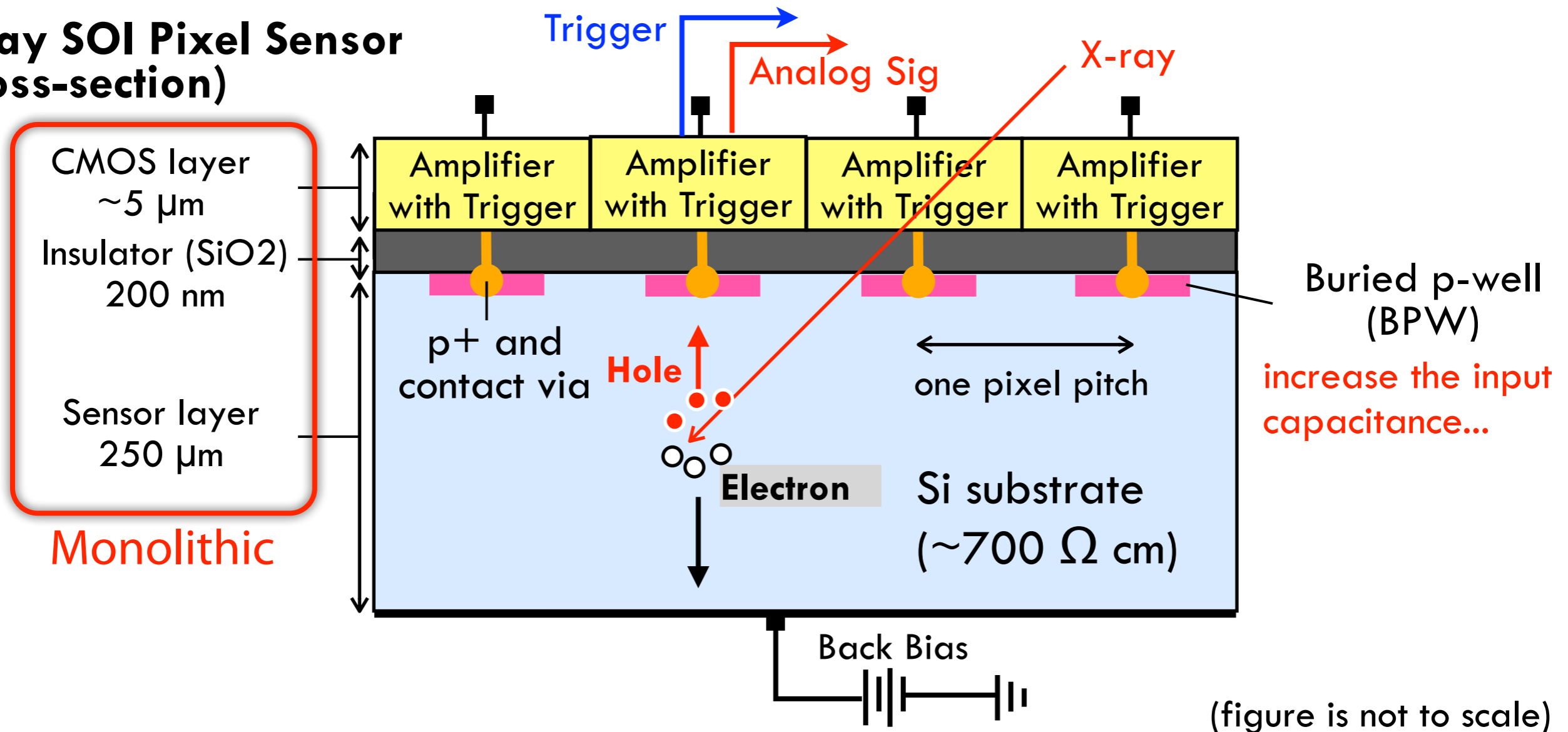
Intra-pixel trigger system achieves

- ▶ **Very fast timing resolution**
- ▶ **Background rejection** with an anti-coincidence system and **wide bandpass**

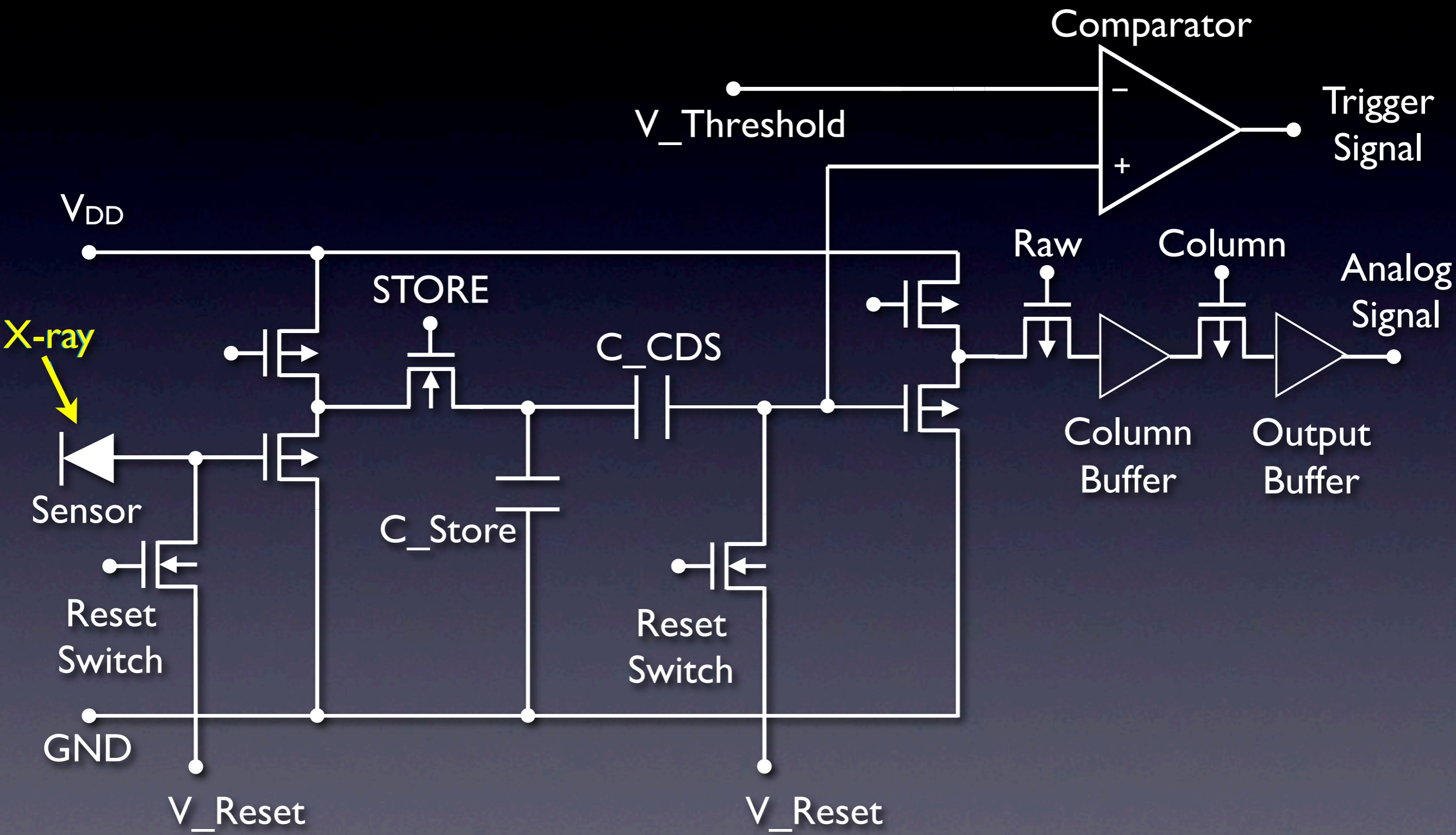


We use Silicon-On-Insulator (SOI) wafer for a new APS

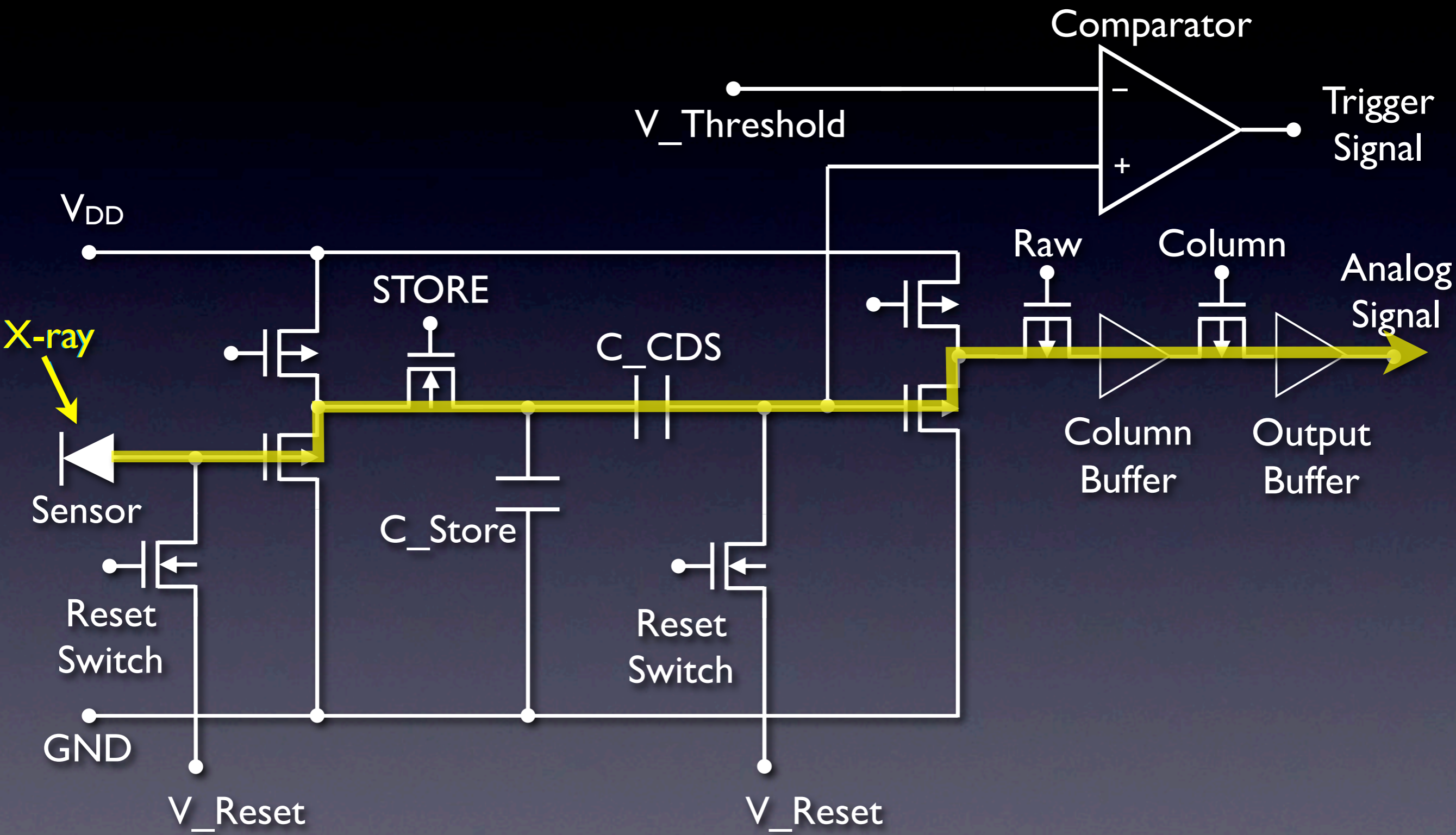
X-ray SOI Pixel Sensor (cross-section)



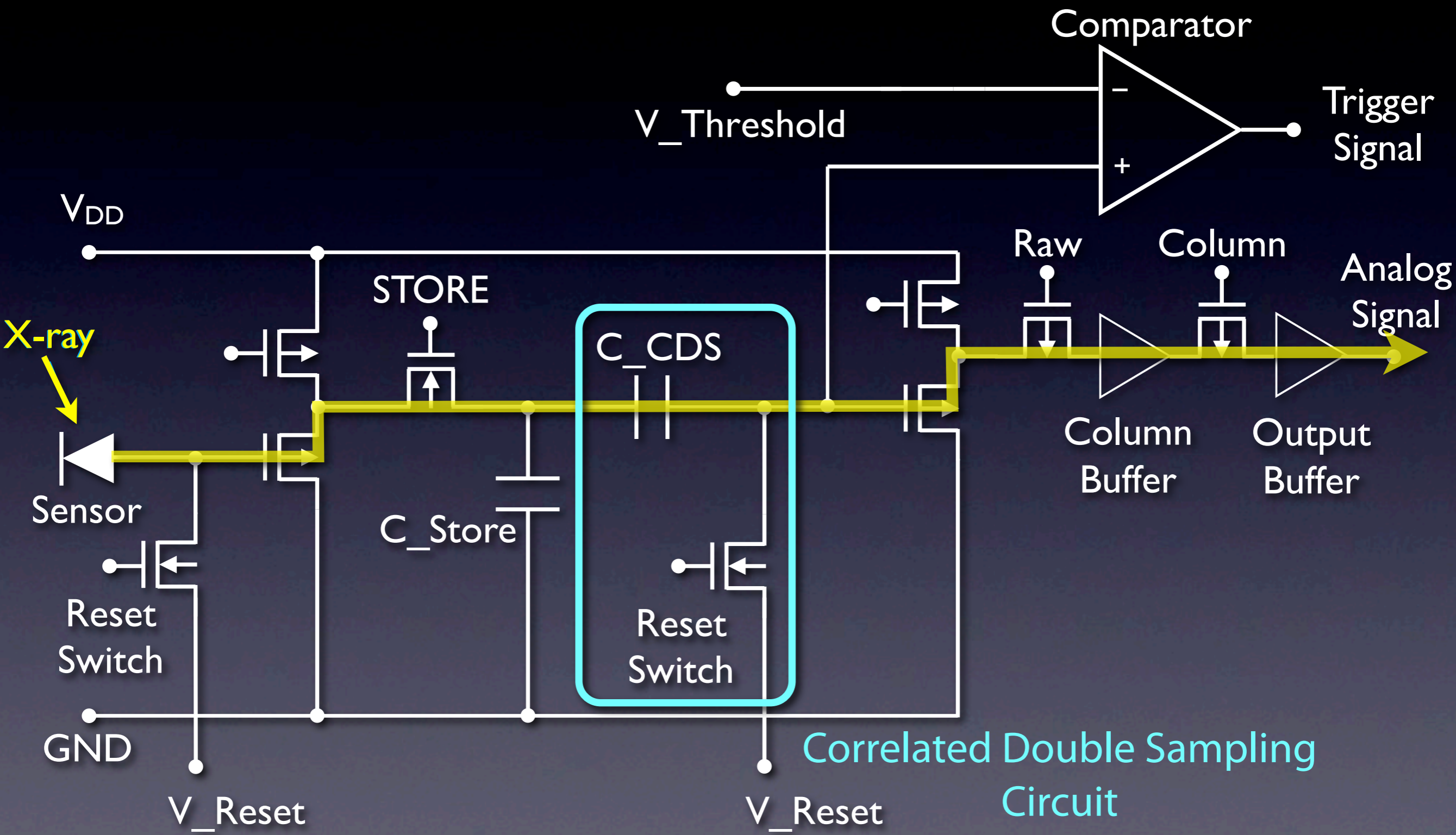
Pixel Circuitry in X-ray SOI Pixel Sensor



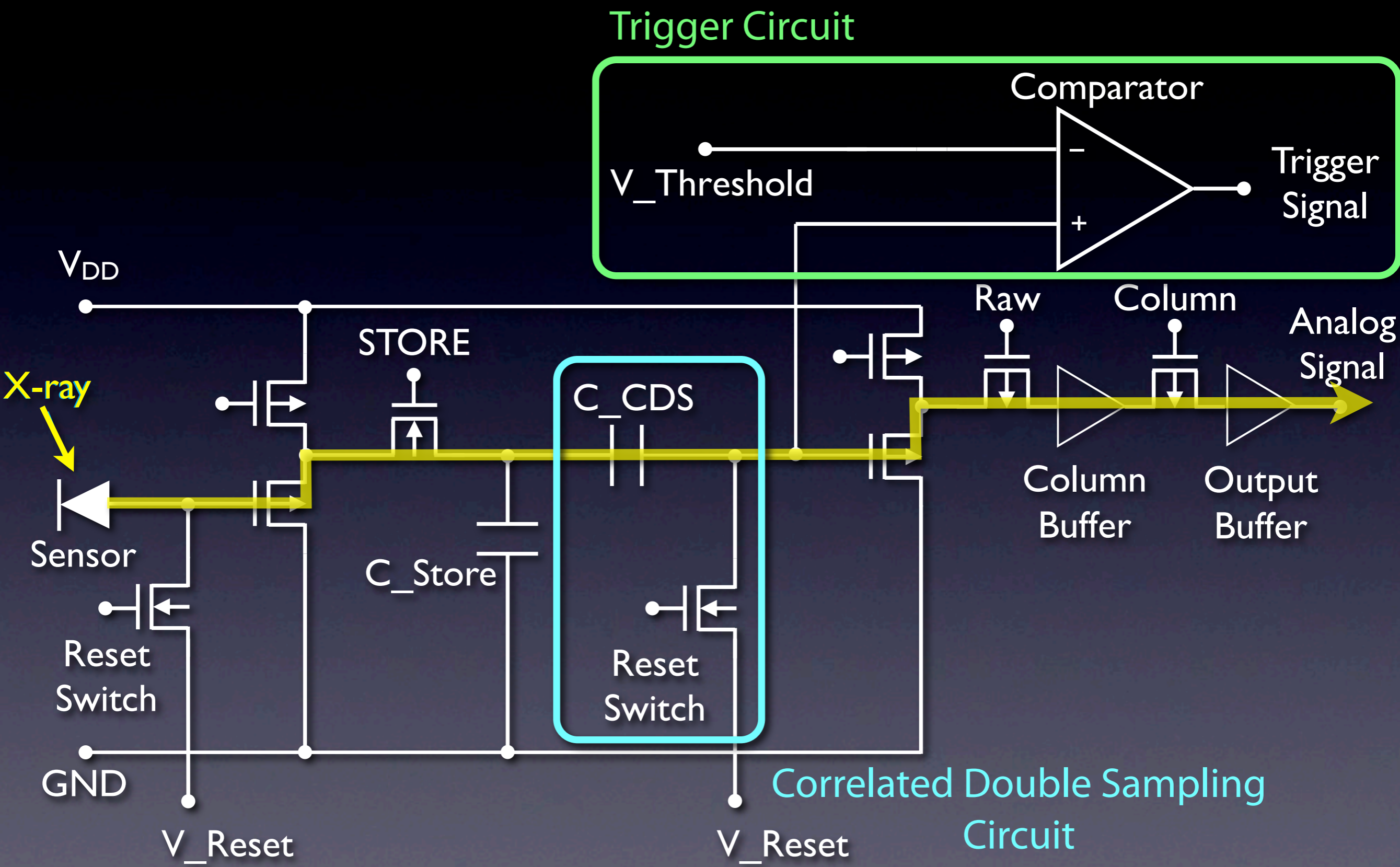
Pixel Circuitry in X-ray SOI Pixel Sensor



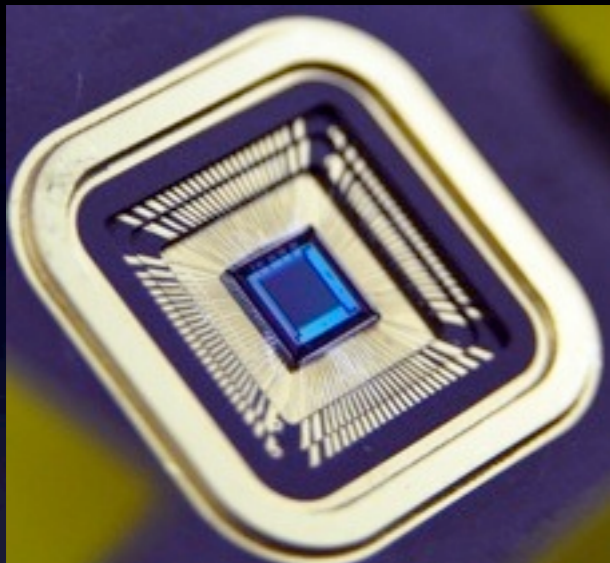
Pixel Circuitry in X-ray SOI Pixel Sensor



Pixel Circuitry in X-ray SOI Pixel Sensor



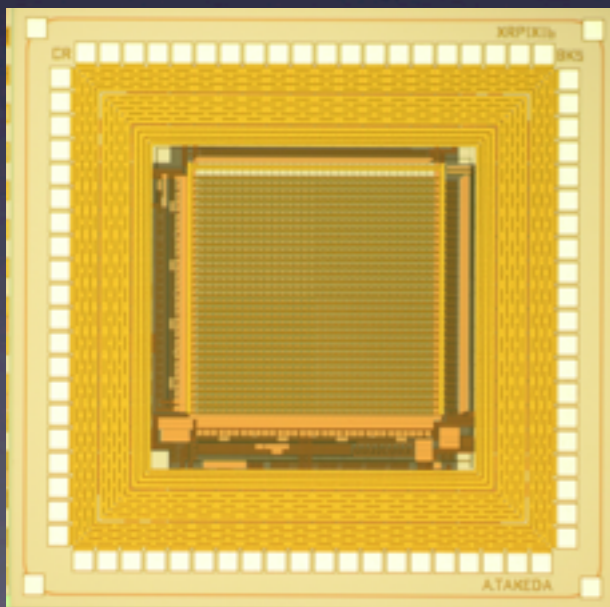
XRPIX1 in 2010



Achievements

- ▶ Small pixel pitch ($<30 \mu\text{m}$)
- ▶ Trigger-driven readout of X-ray signals
- ▶ Full depletion of the sensor layer ($250 \mu\text{m}$)
- ▶ Small crosstalk in adjacent pixels ($<0.5\%$)

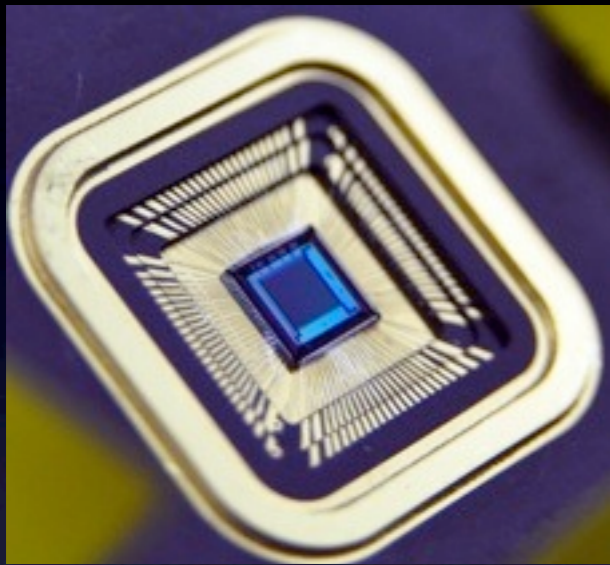
XRPIX1b in 2011



Issues

- ▶ Poor energy resolution in full frame readout ($\sim 1.2 \text{ keV}$ @ 8 keV X-ray)
- ▶ Gain degradation in the trigger-driven readout
- ▶ Backside illumination test
- ▶ Anti-coincidence test

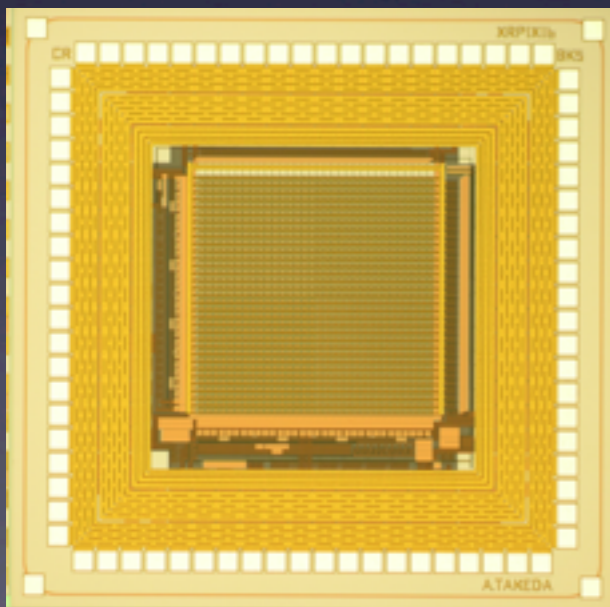
XRPIX1 in 2010



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XRPIX1b in 2011



Issues

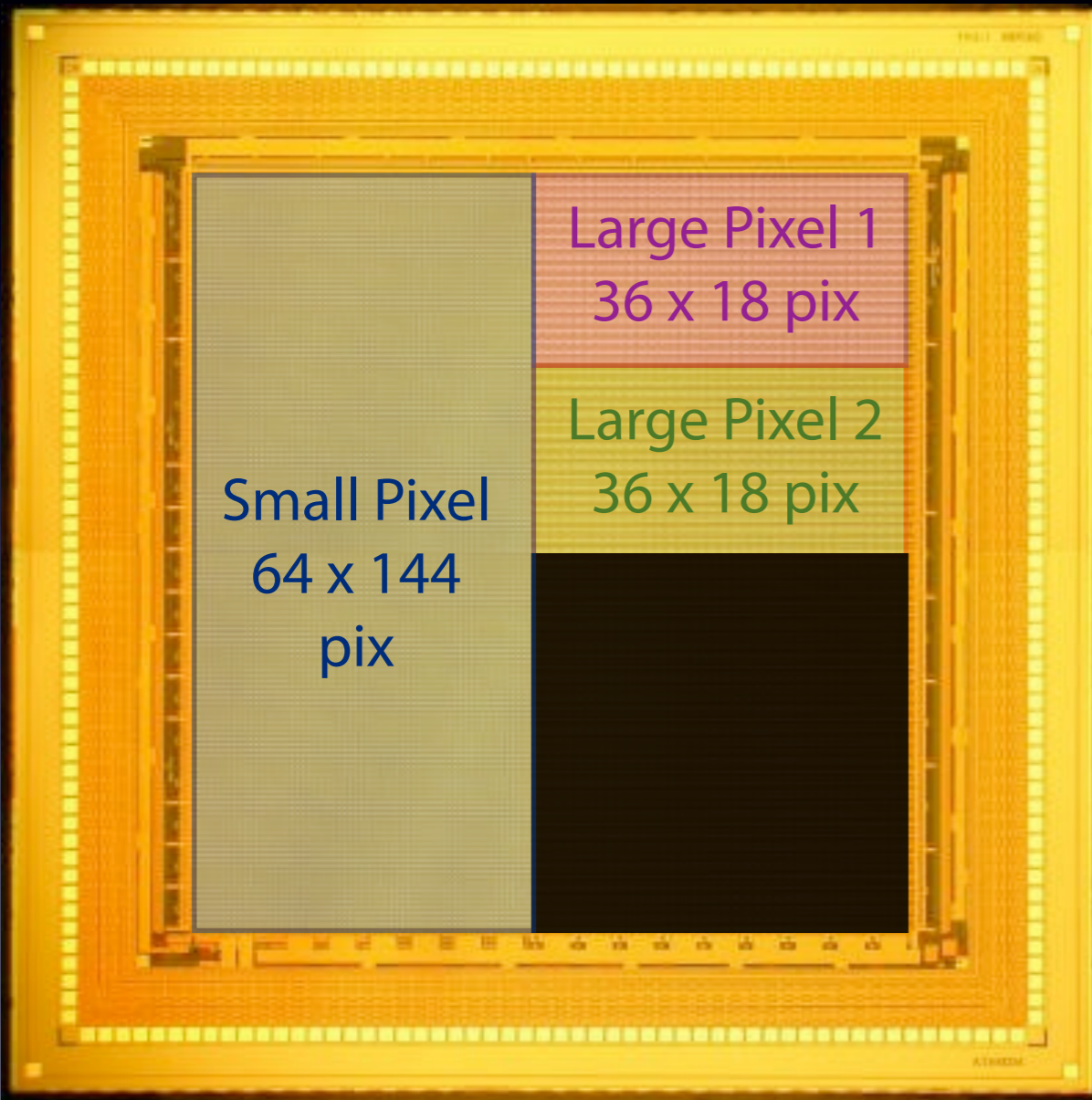
most important issue !

- ▶ Poor energy resolution in full frame readout ($\sim 1.2\ \text{keV}$ @ $8\ \text{keV}$ X-ray)
- ▶ Gain degradation in the trigger-driven readout
- ▶ Backside illumination test
- ▶ Anti-coincidence test

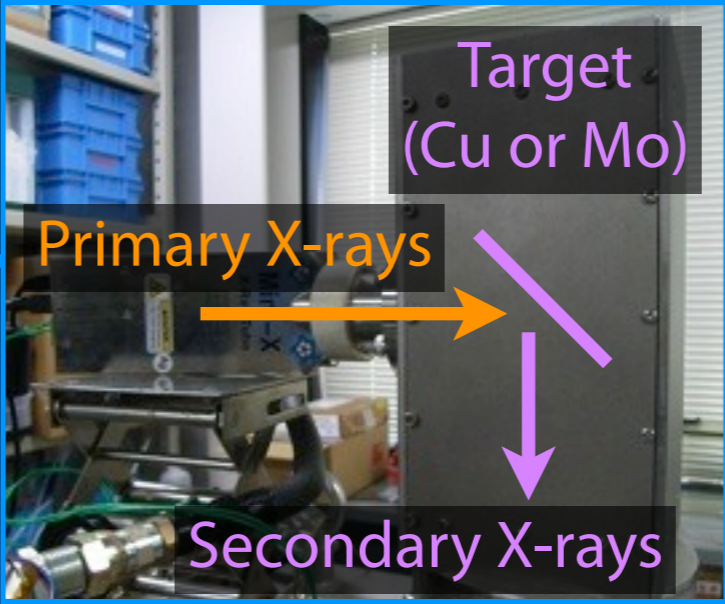
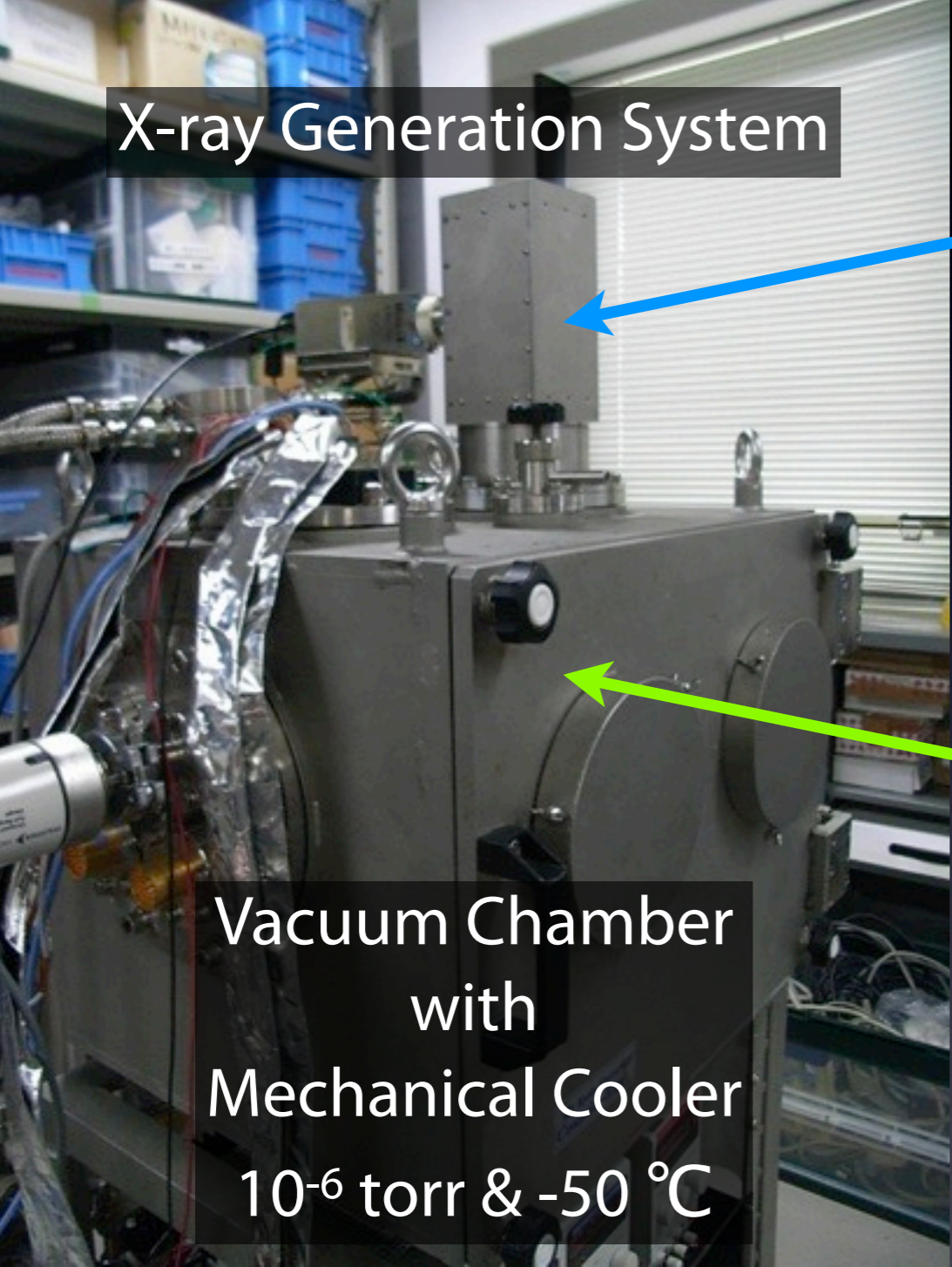
We developed XRPIX2 to improve the spectroscopic performance

Chip design:

- ▶ 0.2 μm FD-SOI process provided by Lapis semiconductor Co. Ltd.
- ▶ Resistivity in the sensor layer = 700 $\Omega\text{ cm}$
- ▶ Resistivity in the CMOS layer = 18 $\Omega\text{ cm}$
- ▶ 2 type pixel pitch (30 μm & 60 μm)

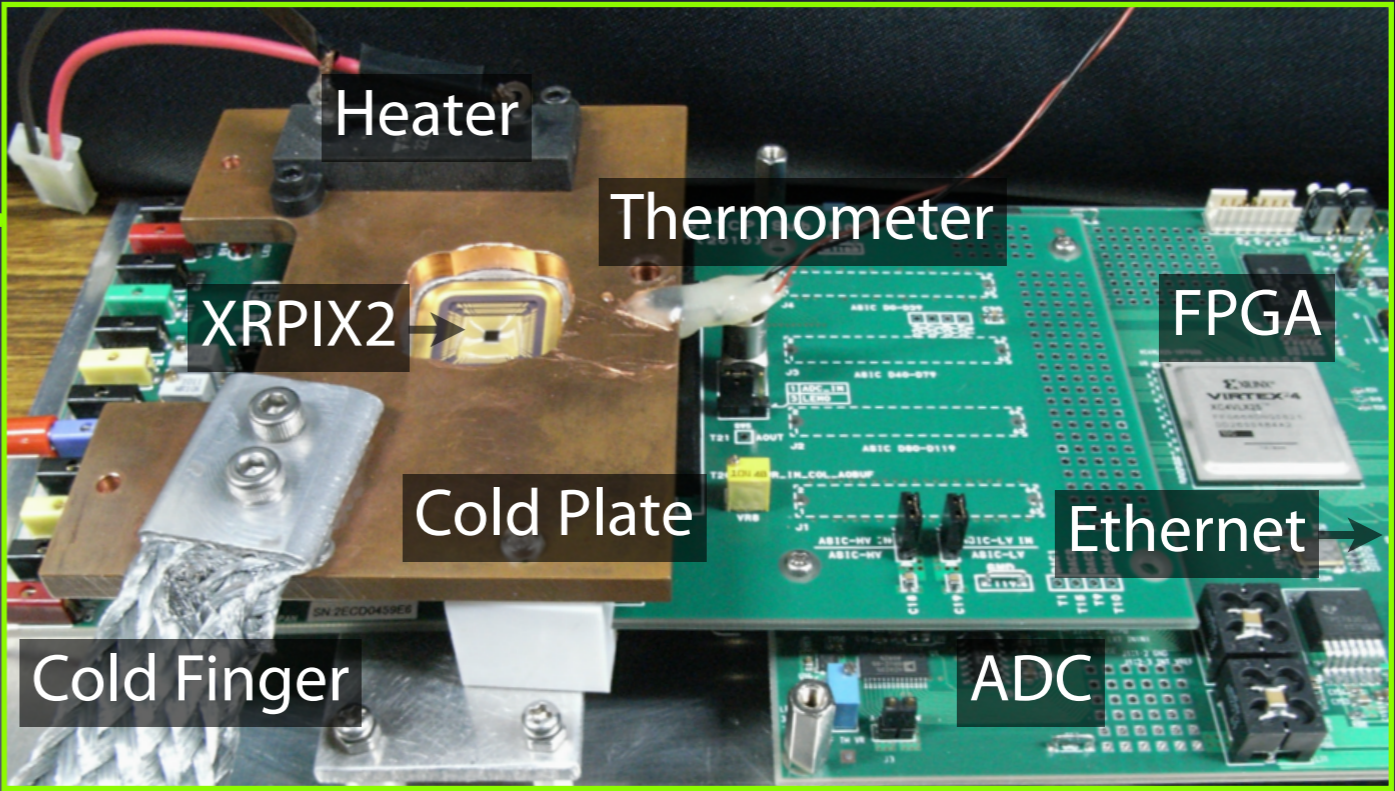


Scope of this presentation is characterization of the XRPIX2

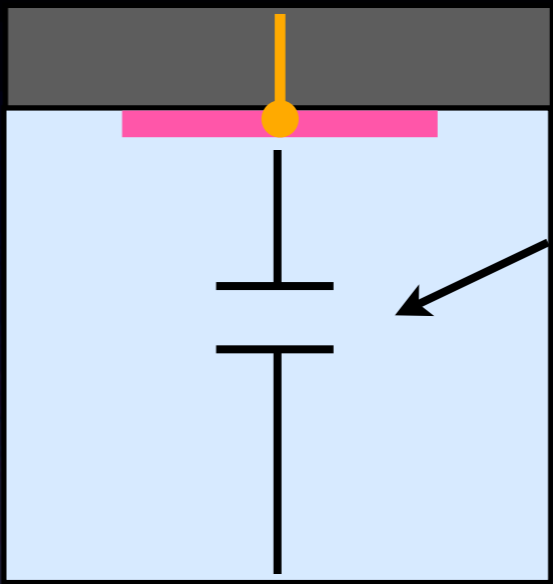


Primary X-rays:
Mini-X, 30 kV 0.1 mA
Ag fluorescence
+ bremsstrahlung

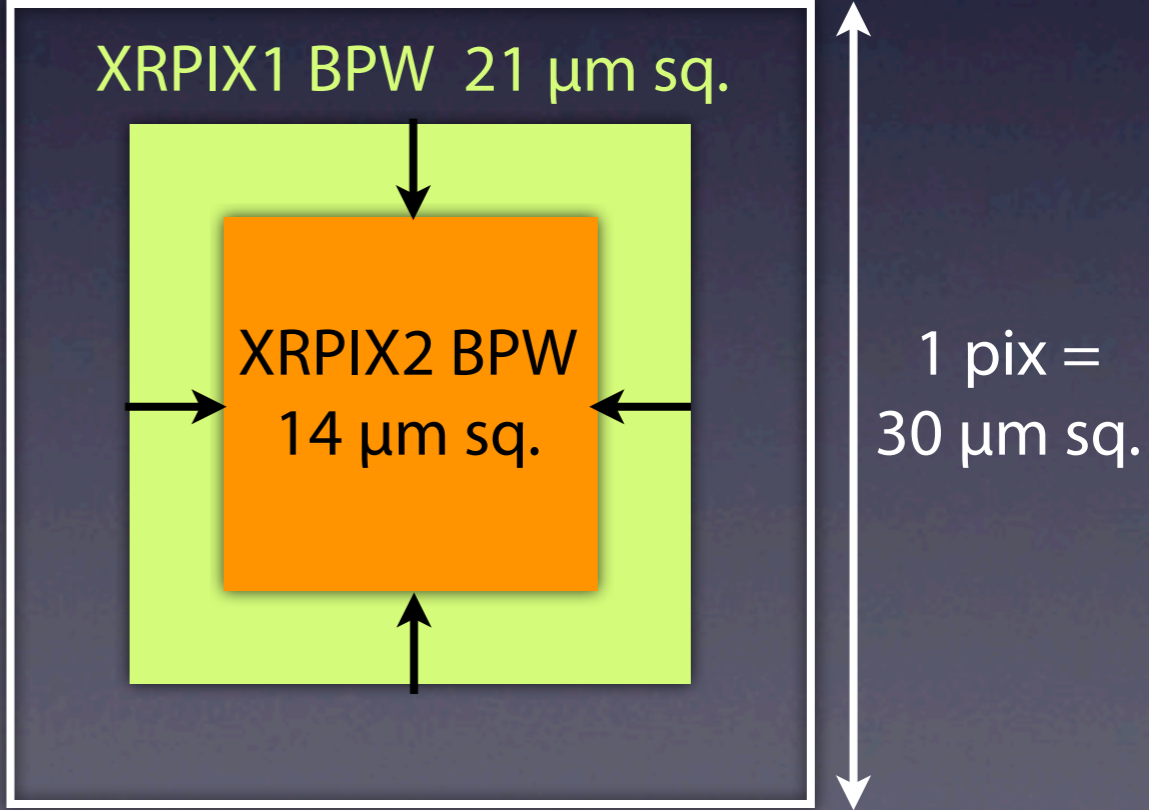
Secondary X-rays:
Cu fluorescence or
Mo fluorescence



Object of Small Pixel -> Increasing the Gain and check Uniformity

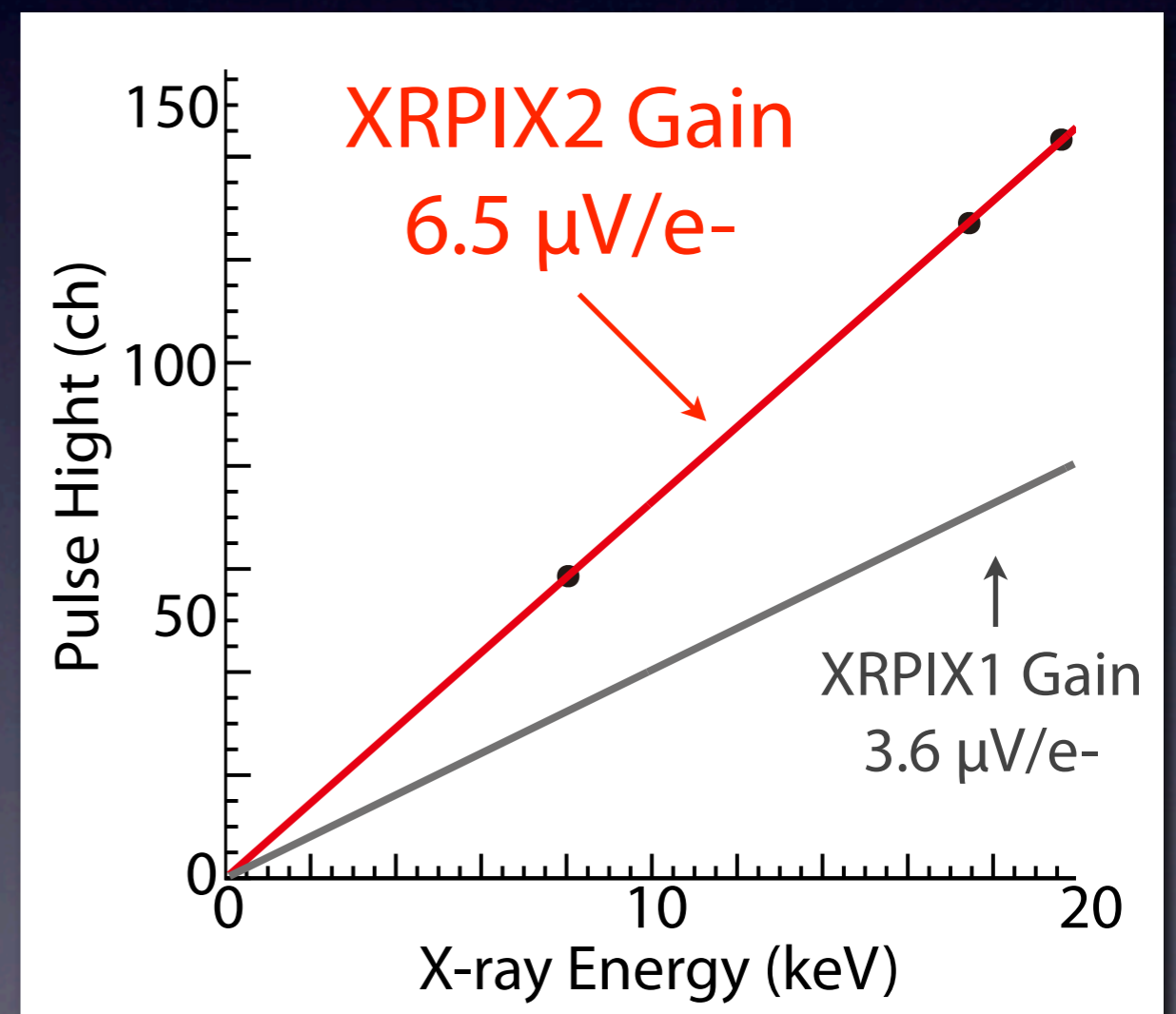
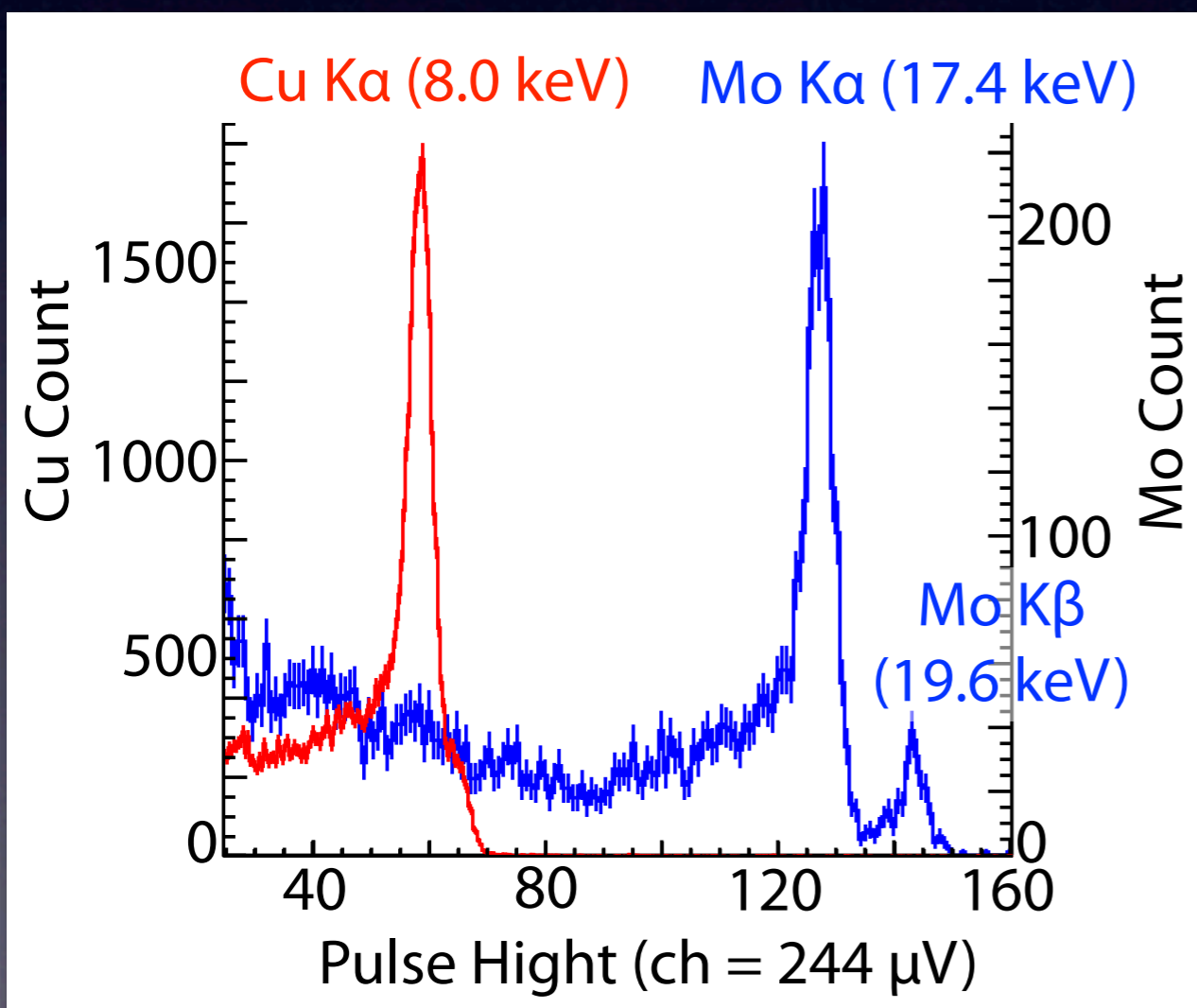
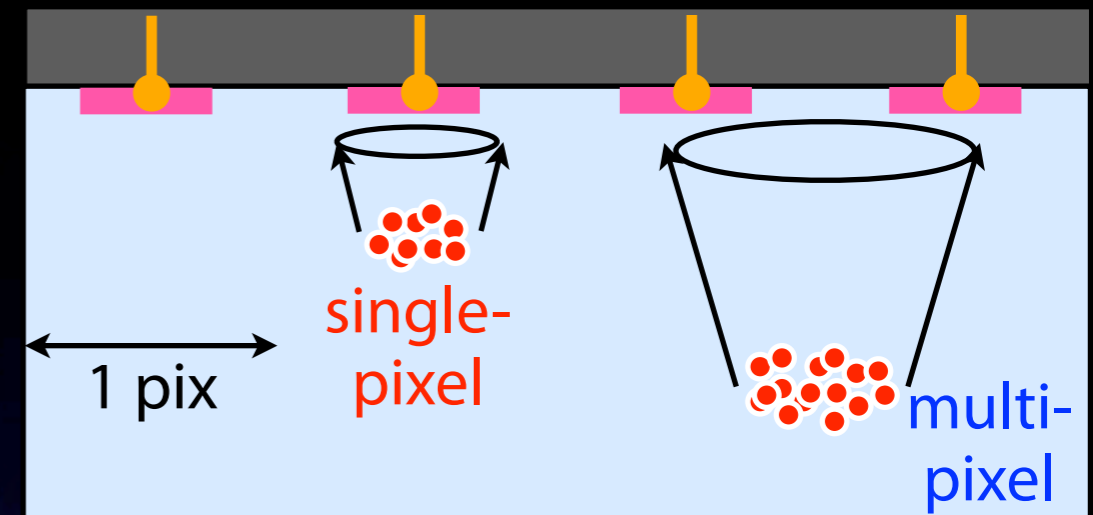


BPW increases the input capacitance
Capacitance \propto Area



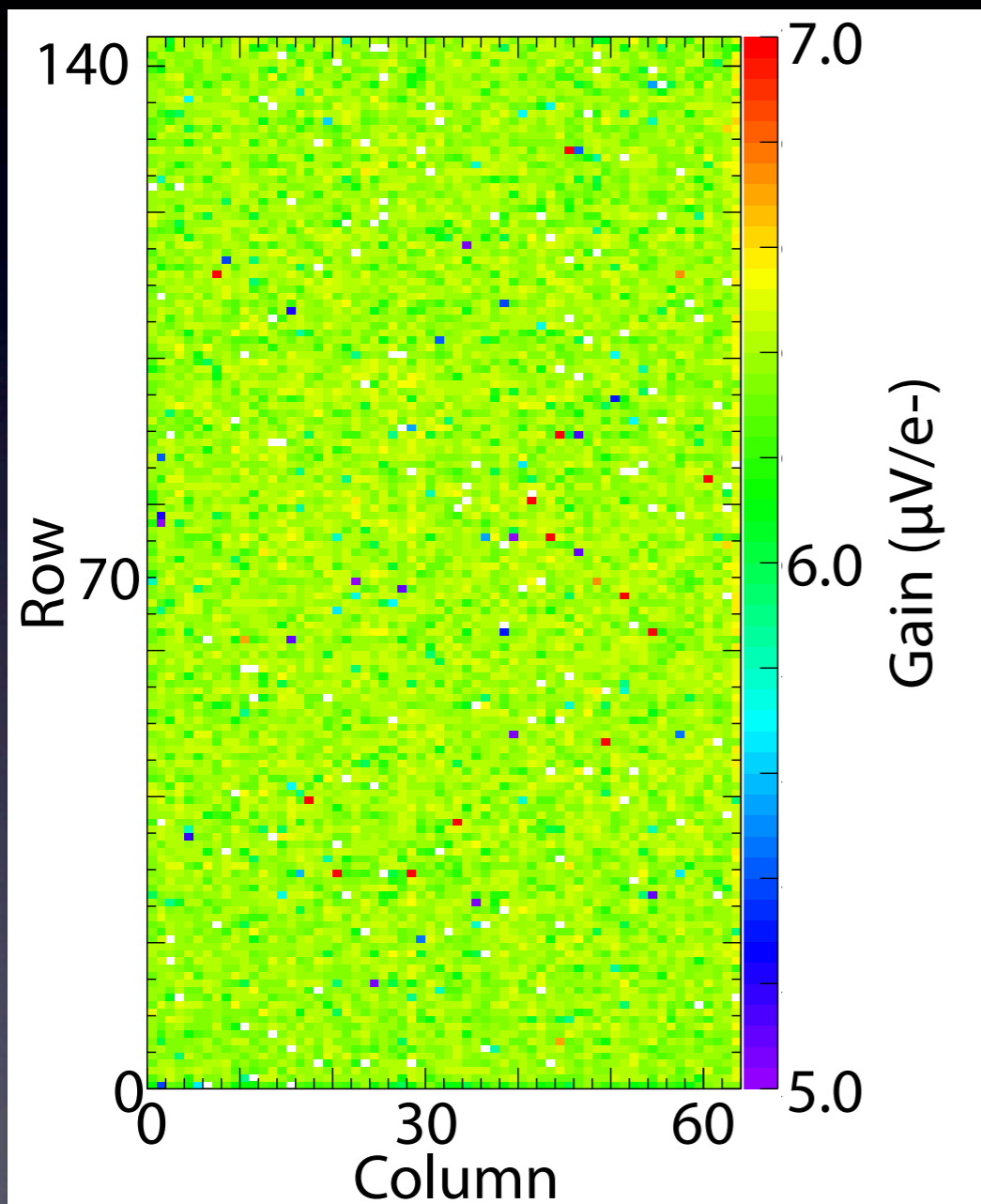
- ▶ Half BPW area ($400 \mu\text{m}^2 \rightarrow 200 \mu\text{m}^2$)
- ▶ Large pixel format (256 pix \rightarrow 9216 pix)

- ▶ Full-frame readout (not trigger driven readout)
- ▶ X-ray event selection
 - discard multi-pixel (charge sharing) events and pick up only single-pixel events

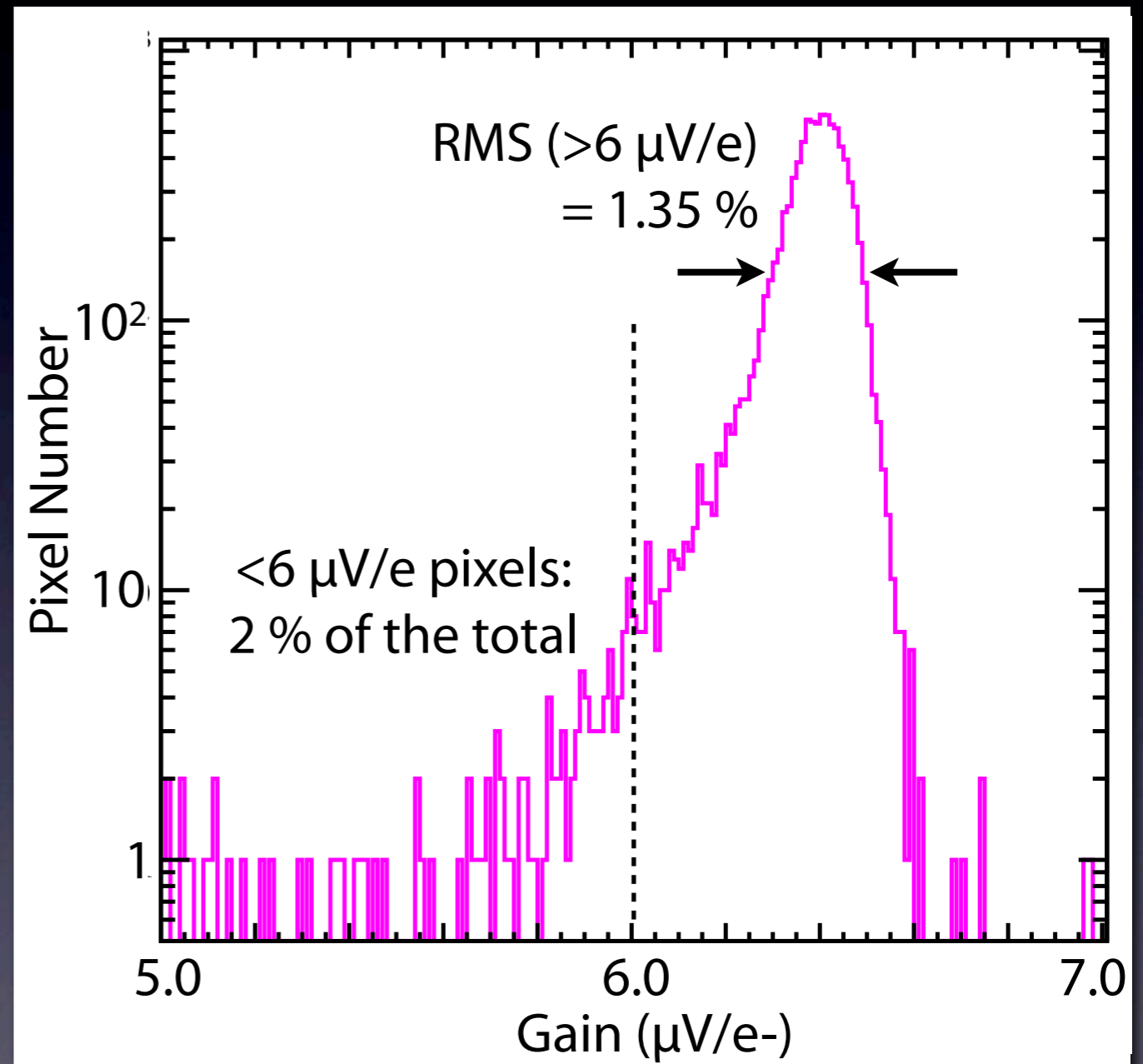


▶ Gain of XRPIX2 is 1.8 times higher than that of XRPIX1

Gain map



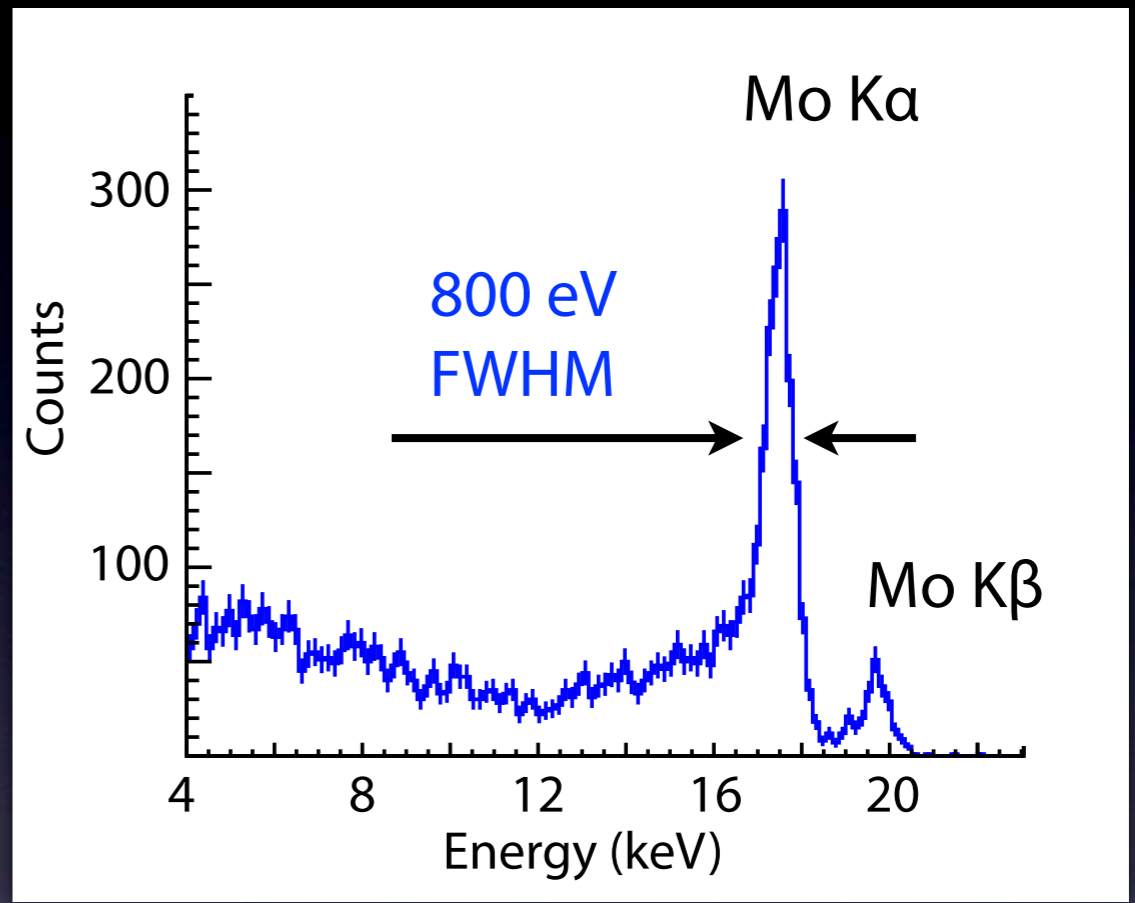
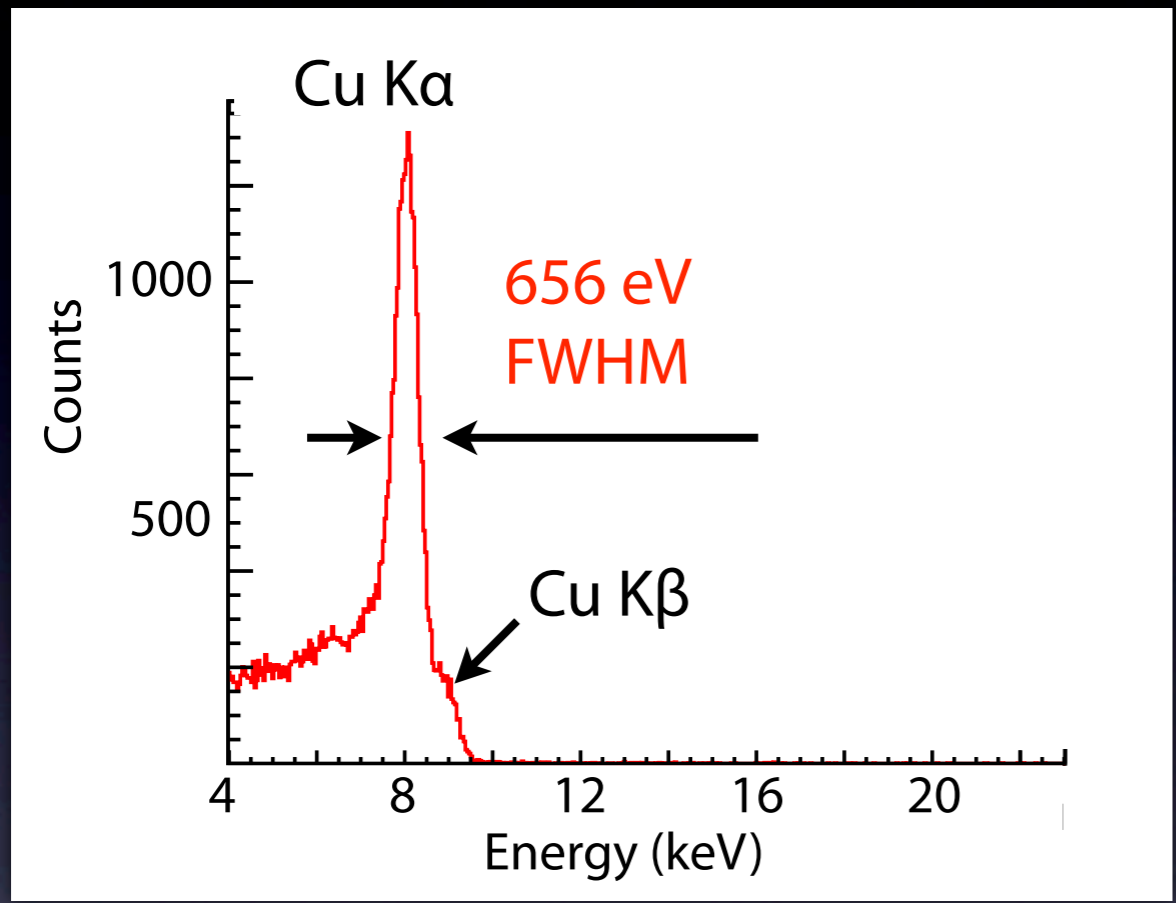
Gain histogram



► Gain uniformity is very good even with the large pixel number

Energy Resolution (Small Pixel)

Readout noise = 64 e- (\Leftrightarrow 129 e- in XRPIX1)



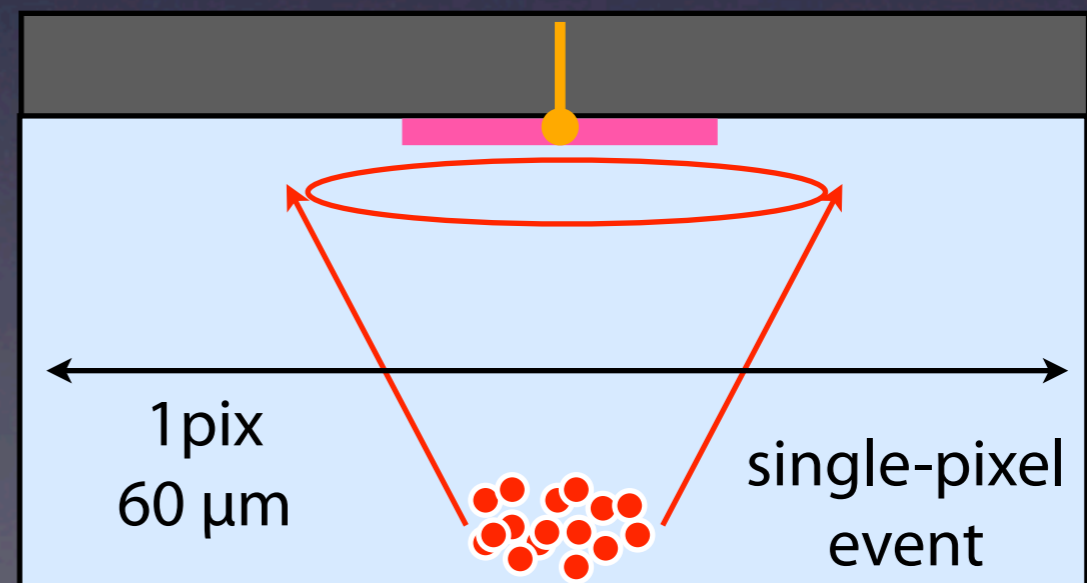
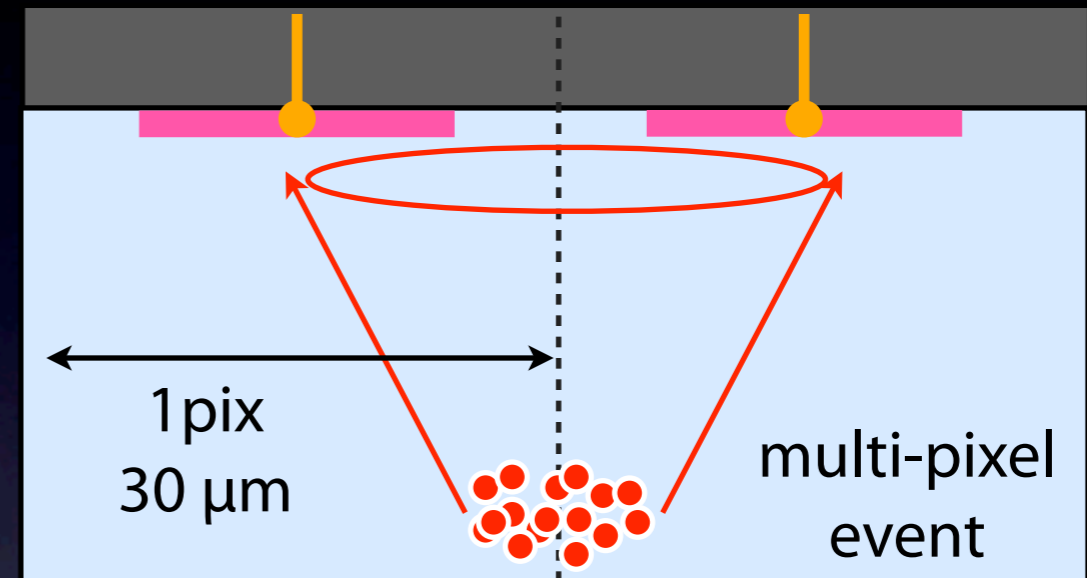
	Readout Noise	Fano Noise	1% Gain Dispersion	Predicted	Observed
Cu K α	548 eV	139 eV	255 eV	620 eV	656 eV
Mo K α		205 eV	553 eV	805 eV	800 eV

► Achieve 1.8 times higher resolution than that of XRPIX1

Object of Large Pixel 1 -> decreasing charge sharing and
Increasing single-pixel events



- ▶ Same layout of Small Pixel
- ▶ Twice pixel pitch (30 μm -> 60 μm)

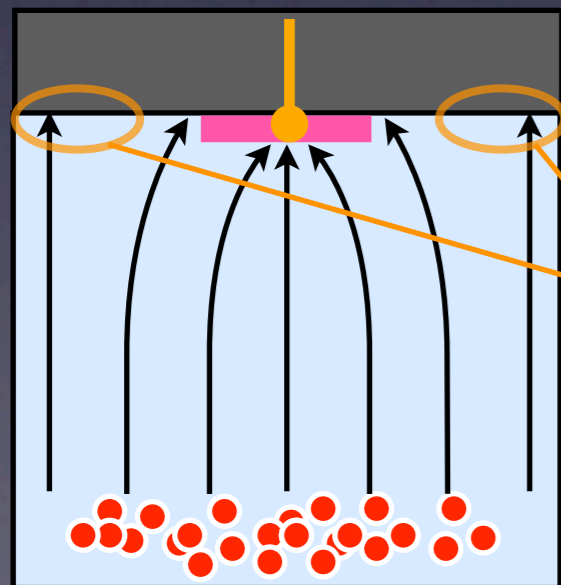


	Single pixel event fraction	
	Small Pixel	Large Pixel 1
Cu K α	86.1%	96.4%
Mo K α	66.5%	86.3%

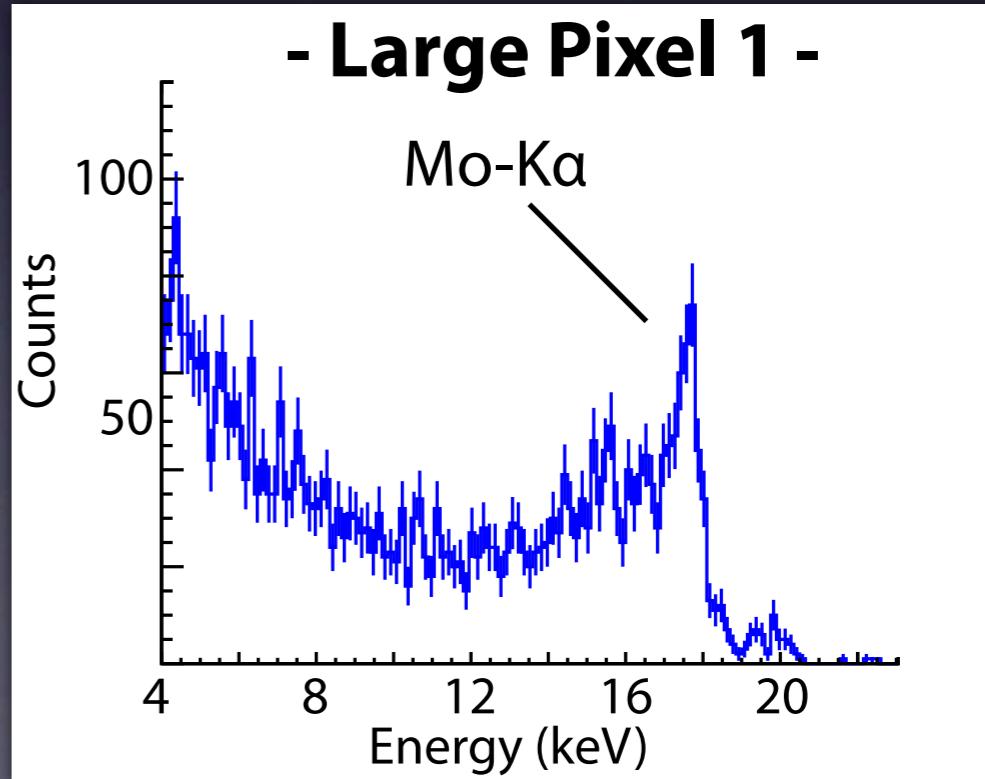
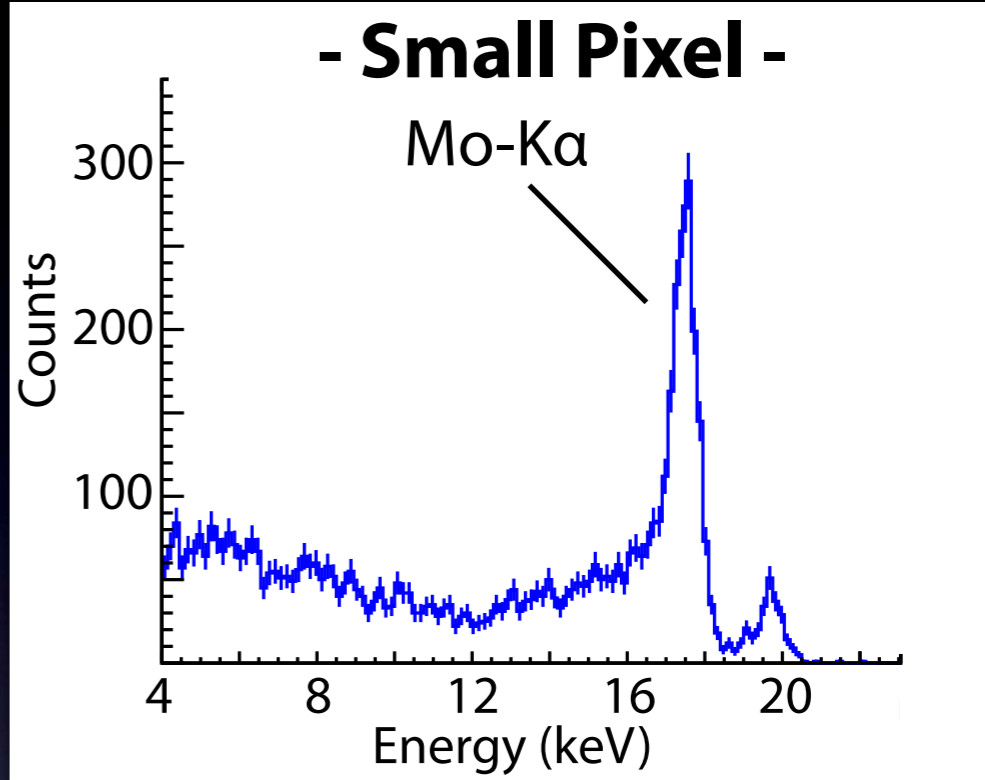
- ▶ Increase single pixel events in Large Pixel 1

	Single pixel event fraction	
	Small Pixel	Large Pixel 1
Cu K α	86.1%	96.4%
Mo K α	66.5%	86.3%

- ▶ Increase single pixel events in Large Pixel 1
- ▶ Spectral shape is obviously worse than Small Pixel



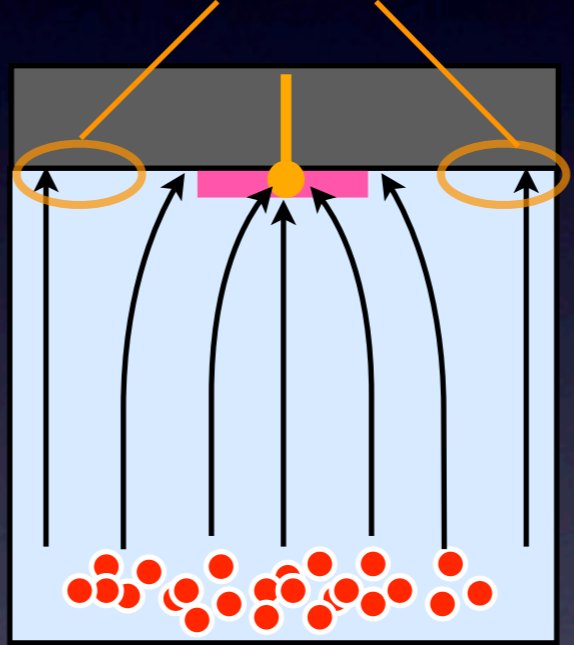
charge collection inefficiency at the pixel edge



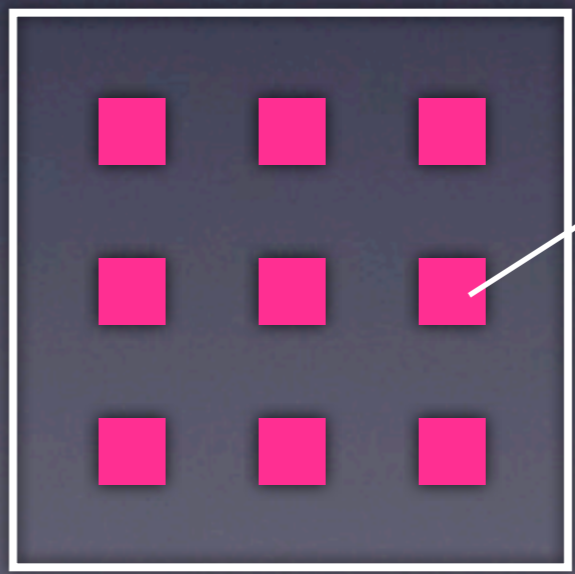
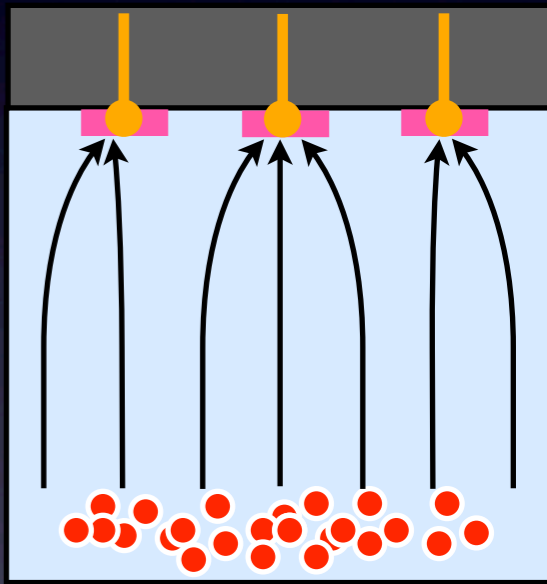
Object of Large Pixel 2 -> Improving the charge collection efficiency



low charge collection efficiency at the pixel edge

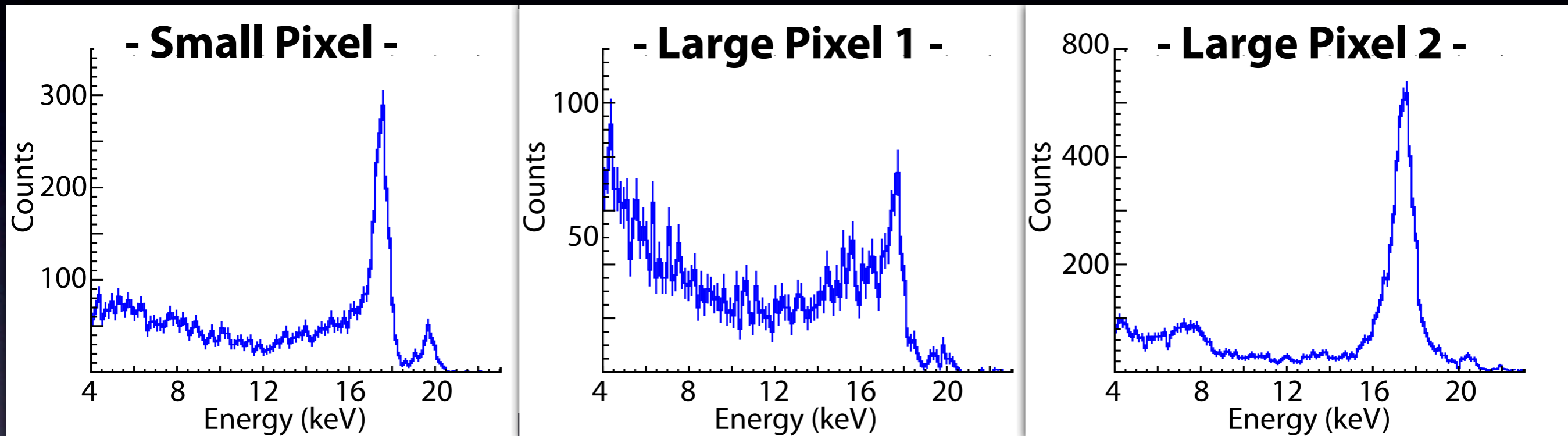


Multi-via structure can improve efficiency

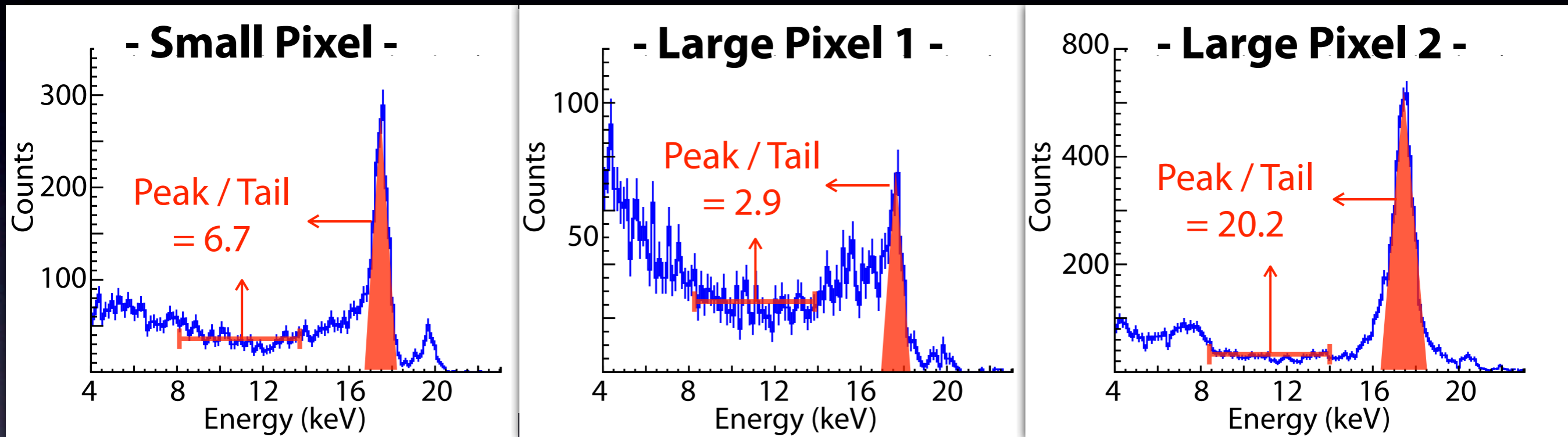


Via + Small BPW

- ▶ 9 vias + BPWs
- ▶ Total BPW area = 130 μm^2



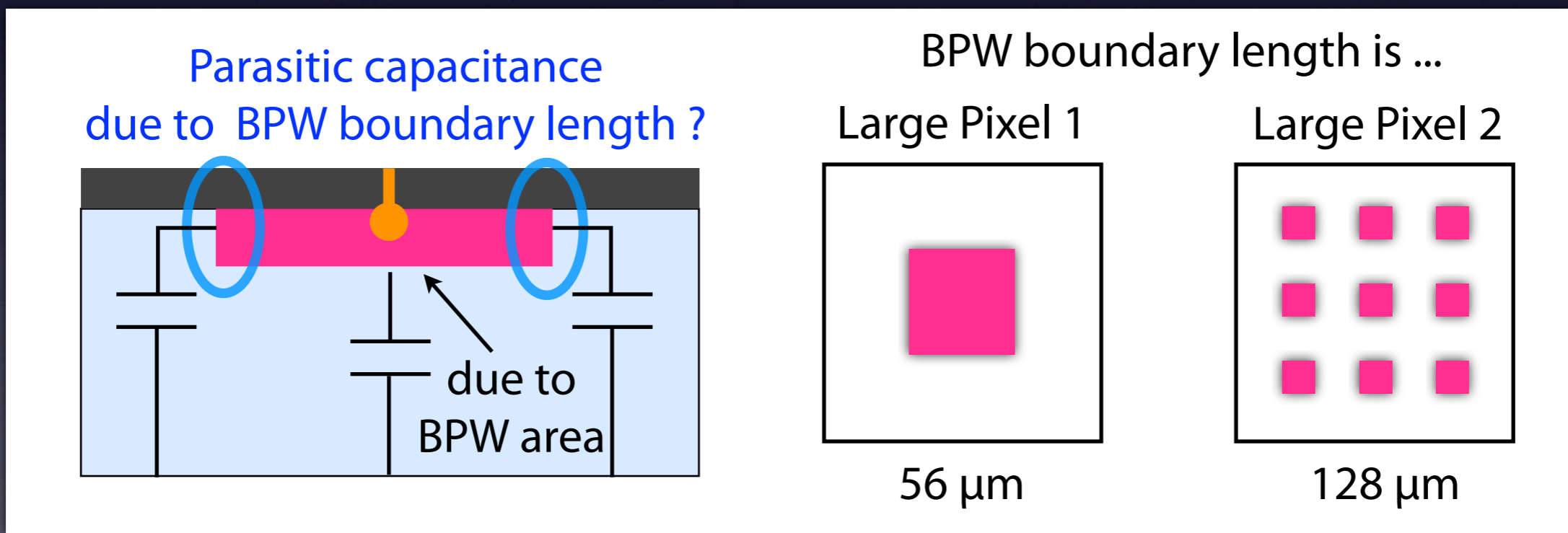
- ▶ Multi-via structure successfully improves the charge collection efficiency.



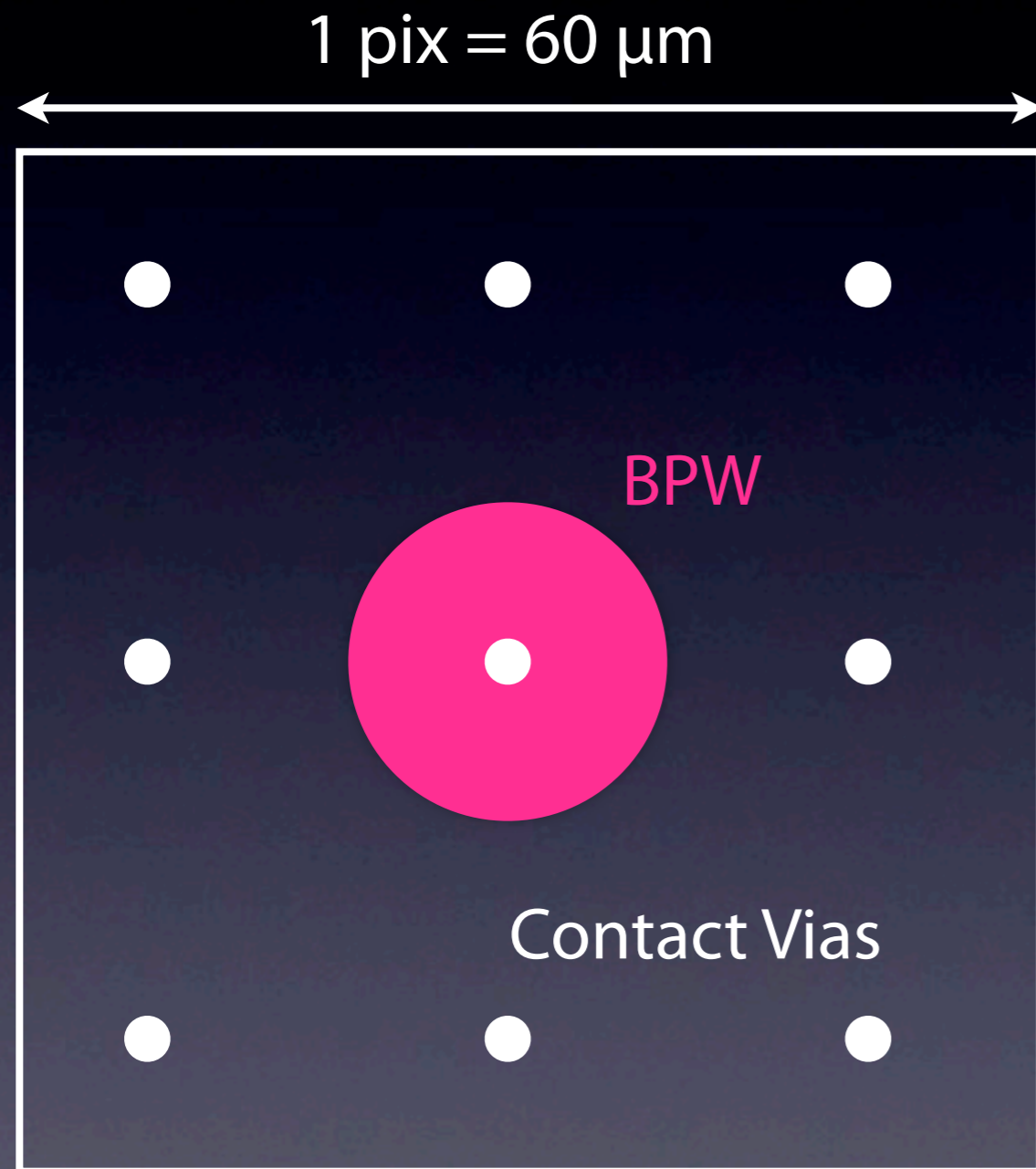
- ▶ Multi-via structure successfully improves the charge collection efficiency.

	Small Pixel	Large Pixel 1	Large Pixel 2
Gain	6.5 μV	6.5 μV	$\xrightarrow{1/2}$ 3.3 μV

Why does gain decrease in Large Pixel 2 ?



► Simulation for confirmation is underway.



- ▶ Large Pixel Size
 - > Reduce charge sharing
- ▶ Multi-via Structure
 - > Increase charge collection efficiency
- ▶ One BPW
 - > Increase the gain
- ▶ Intra-pixel Charge Amplifier
 - > Increase the gain

Summary

- ▶ We are developing X-ray SOI pixel sensor for X-ray Astronomy.
- ▶ New device, "XRPIX2", achieve 1.8 times higher gain and energy resolution than that of XRPIX1. (Gain = $6.5 \mu\text{V}/e^-$, Energy resolution = $656 \text{ eV @}8 \text{ keV}$)
- ▶ Large pixel pitch decreases charge sharing and multi-via structure improves the spectral shape.

Ongoing Work

- ▶ Feedback the results into the next chip design.
- ▶ Trigger driven readout with XRPIX2.